



DEFENSE LOGISTICS AGENCY
 DEFENSE SUPPLY CENTER, COLUMBUS
 POST OFFICE BOX 3990
 COLUMBUS, OH 43218-3990

IN REPLY
REFER TO

DSCC-VQ (VQE-07-014176 /Jeffrey P. Ciesla/614-692-0624/jpc)

August 31, 2007

SUBJECT: Notification of Qualification, MIL-PRF-31032, MIL-P-50884, MIL-PRF-55110,
CAGE Code 4MEG7

Mr. Don Angulo
 Cirexx International
 791 Nuttman Street
 Santa Clara, CA 95054

Dear Mr. Angulo:

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specifications MIL-PRF-31032/2 and MIL-PRF-31032/3. The capabilities by technology indicated below shall be listed on Qualified Manufacturers List QML-31032. Additionally, qualification is granted to the QPL-55110 and QPL-50884 per paragraph 6.3.4 of MIL-PRF-31032, MIL-PRF-55110, and MIL-P-50884. The effective date of this qualification is August 31, 2007.

MANUFACTURER NAME & ADDRESS	PLANT LOCATION	CAGE CODE: 4MEG7
Cirexx International 791 Nuttman Street Santa Clara, CA 95054	Cirexx International 3391 Keller Street Santa Clara, CA 95054	CONTACT: Mr. Don Angulo PHONE #: (408) 988-3980 FAX #: (408) 988-4534 Email: dangulo@cirexxintl.com
CAPABILITIES BY TECHNOLOGY ASSOCIATED SPECIFICATION		QUALIFICATION LETTER:
MIL-PRF-31032/2		VQ 07-014176
Panel Size	12" X 18"	
Max. Board Thickness	0.100"	
Min Plated Hole Size	0.010"	
Aspect Ratio	10:1	
Max. Number of Layers	2	
Min. Conductor Width	0.004"	
Min. Conductor Spacing	0.004"	
Part Mounting	SMT, THM, MIX	
Rigid Base Material	GF (Woven E-Glass, Epoxy Resin)	
Finish System	HASL, Ni/Au, ENIG	
Hole Preparation	Plasma Desmear	
Copper Plating	Acid Copper	
Solder Resist	LPI	

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CAPABILITIES BY TECHNOLOGY ASSOCIATED SPECIFICATION		QUALIFICATION LETTER:
MIL-PRF-31032/3		VQ 07-014176
Panel Size	12" X 18"	
Max. Board Thickness	0.100"	
Min Plated Hole Size	0.010"	
Aspect Ratio	10:1	
Max. Number of Layers	2	
Min. Conductor Width	0.004"	
Min. Conductor Spacing	0.004"	
Part Mounting	SMT, THM, MIX	
Rigid Base Material	GF (Woven E-Glass, Epoxy resin)	
Flex Base Material	Acrylic Adhesive on Polyimide, Coper Clad Adhesiveless Polyimide	
Finish System	HASL, Ni/Au, ENIG	
Hole Preparation	Plasma Desmear	
Copper Plating	Acid Copper	
Solder Resist	Kapton Coverlay	

Test report number 31032-1966-07 has been assigned to your test data. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.



6. The listing shall appear on the next issue of Qualified Manufacturers List QML-31032 in addition to reciprocal listings on the QPL-55110 and QPL-50884.

Manufacturers are required to inform this office immediately if a failure occurs during PCI or CVI testing, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Jeffrey Ciesla, (614) 692-0624.

Sincerely,



ROBERT EVANS

Chief

Sourcing and Qualifications Unit